



APG2C1-720



IR High Power single chip LED

APG2C1-720 is an GaAlAs based, high power 720 nm single chip LED in standard emitter package for general application.

Specifications

- Structure: GaAlAs
- Peak Wavelength: 720 nm
- Optical Output Power: typ. 100 mW
- Life Time: > 10.000 hours
- Housing: standard emitter package



Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Power Dissipation, DC	P_D	1000	mW
Forward Current, DC	I_F	500	mA
Pulsed Current (1% duty cycle, 1kHz)	I_{FP}	1000	mA
Reverse Voltage	U_R	-5	V
Operating Temperature	T_{opr}	-30 ... +70	$^\circ\text{C}$
Storage Temperature	T_{stq}	-30 ... +85	$^\circ\text{C}$
Soldering Temperature (max. 1,5 s)	T_{sol}	330	$^\circ\text{C}$

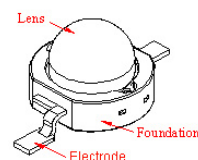
Electro-Optical Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Current	I_F		-	350	-	mA
Viewing Angle	ϕ	$I_F = 350 \text{ mA}$		± 75		deg.
CW Output Power	P_O	$I_F = 350 \text{ mA}$		100		mW
Peak Wavelength	λ_p	$I_F = 350 \text{ mA}$	705	715	725	nm
Forward Voltage	U_F	$I_F = 350 \text{ mA}$	-	1.9	-	V
Half Width (FWHM)	$\Delta\lambda$	$I_F = 350 \text{ mA}$	-	25		nm
Switching time	T_R, t_F	$I_F = 350 \text{ mA}$		40		ns

Wavelength measurements tolerance is +/- 2%
Output power measurement tolerance is +/- 10%
Voltage measurement tolerance is +/- 2%

Device Materials

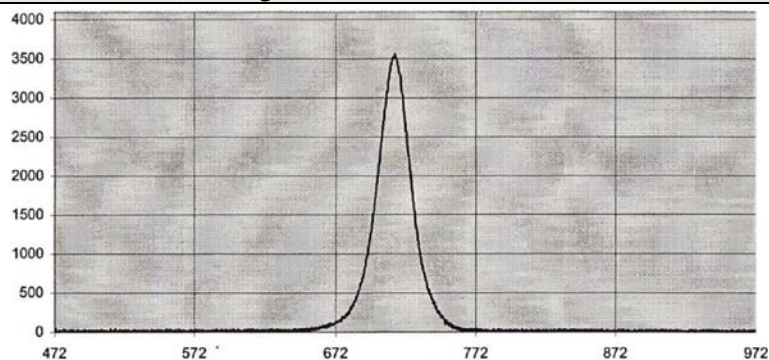
Item	Material
Foundation	Plastic
Lens	Acryl
Electrodes	AgCu
Heat Sink	AgCu





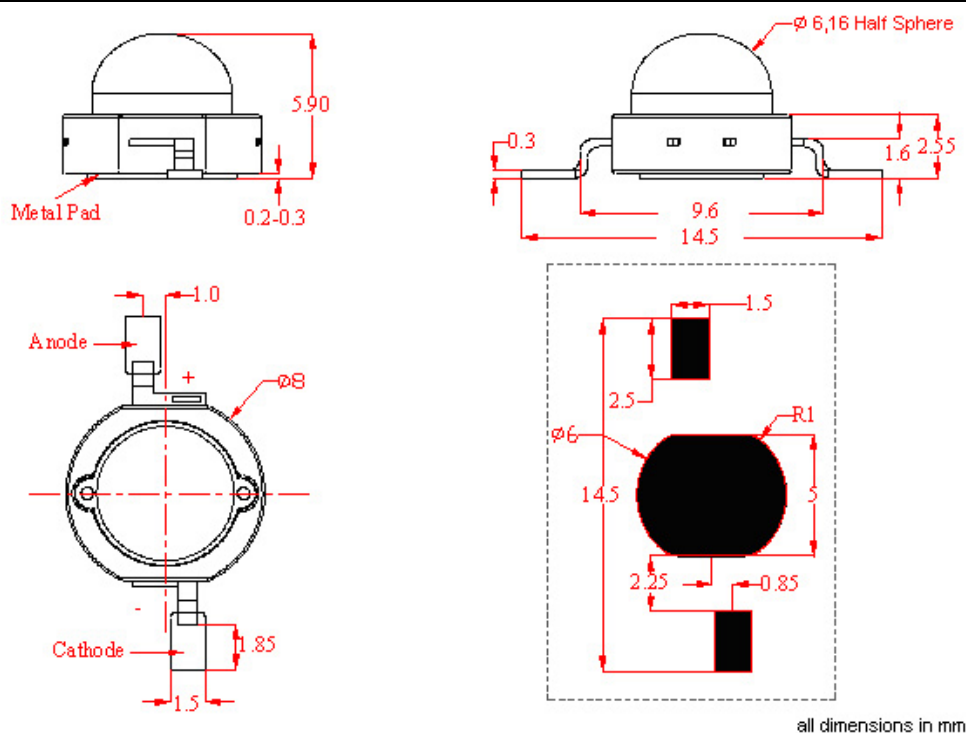
Typical Performance Characteristics

Normalized Output Power vs. Wavelength:



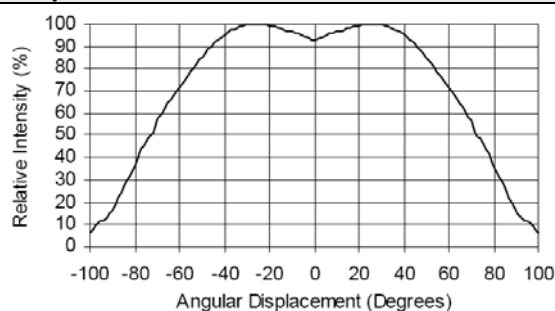
Outline Dimensions

Emitter:



Radiation Pattern (Lambertian lens without optics)

Relative Intensity vs. Angular Displacement





Soldering Conditions

Reflow Soldering:

APG2C1 LEDs have a maximum storage temperature of 85°. Therefore it is not possible to use a reflow soldering process for array assembly!

Hot Bar Soldering:

A Hot Bar Soldering process is recommended when soldering APG2C1 emitters. This process will only transfer heat to the leads and avoids overheating the emitter which will damage the device. In order to transfer sufficient heat from the hot bar to the device, following parameters must be carefully considered:

- Amount of flux
- Pressing force of solder tip
- Hot bar temperature

For the standard assembly process, following parameters should be maintained:

- Hot Bar temperature: 330 °C
- Force of Hot Bar: 40 N
- Soldering time: 1.5 s

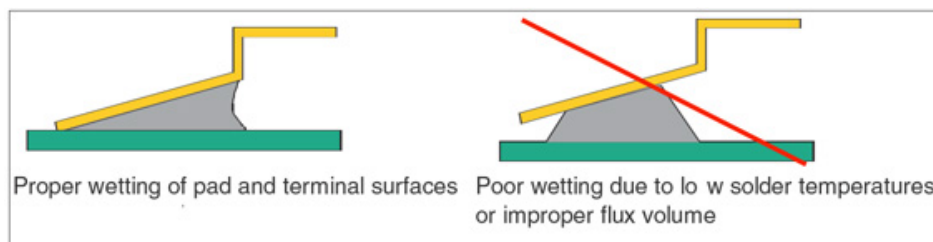
It is recommended to use a copper nickel-plated hot bar mounted to standard temperature controlled soldering equipment.

Manual Hand Soldering:

For prototype build or small series production runs, it is possible to place and solder the emitters by hand. It is therefore recommended to maintain the following parameters:

- Solder Tip Temperature 330 °C
- Soldering time: < 1.5 s
- Junction temperature must be kept below 70 °C

A visual inspection may be used to check the quality of the solder joint



General Soldering Precautions:

- Mechanical stress, shock and vibration must be avoided during soldering
- Only use non corrosive flux.
- Do not apply current to the device until it has cooled down to room temperature after soldering.



NOTE
HIGH POWER LED
MUST BE COOLED